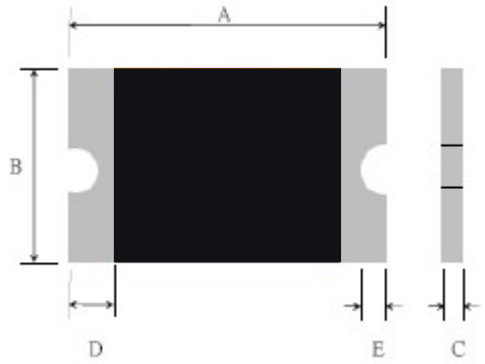
TERMINAL PAD SOLDERABILITY：

Meets EIA Specification RS186-9E
And ANSI/J-STD-002 Category 3.



TERMINAL PAD MATERIALS：

Tin-Plated Nickel-Copper
Lead-Free，ROHS Compliant

TABLE I. DIMENSIONS： Unit：mm

Model	A		B		C		D	E
	Min	Max	Min	Max	Min	Max	Min	Min
1812-050/15V	4.37	4.73	3.07	3.41	0.40	0.90	0.30	0.25

TABLE II. PERFORMANCE RATINGS：

Model	Vmax	Imax	Ihold@25℃	Itrip@25℃	Pd Typ.	Maximum Time TO Trip		Resistance		
	(Vdc)	(A)	(A)	(A)	(W)	Current (A)	Time (Sec)	Rimin (Ω)	Rityp (Ω)	Rimax (Ω)
1812-050/15V	15.0	100	0.50	1.00	0.8	8.0	0.15	0.150	0.250	1.000

Note:

Ihold=Hold current:maximum current device will pass without tripping in 23℃ still air.

Itrip=Trip current:minimum current at which the device will trip in 23℃ still air.

Vmax=Maximum voltage device can withstand without damage at rated curre（Imax）.

Imax=Maximum fault current device can withstand without damage at rated v（Vmax）.

Pd=Power dissipated from device when in the tripped state at 23℃ still air.

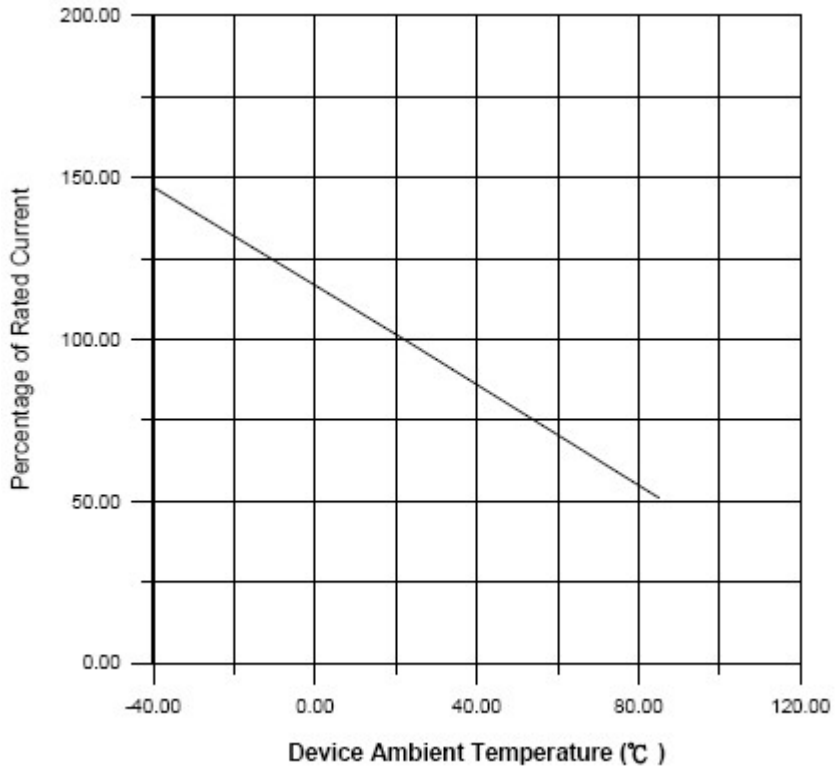
Rmin=Minimum resistance of device in initial （un-soldered）state.

R1max=Maximum resistance of device at 23℃ measured one hour after tripping or reflow soldering of 260℃ for 20sec.

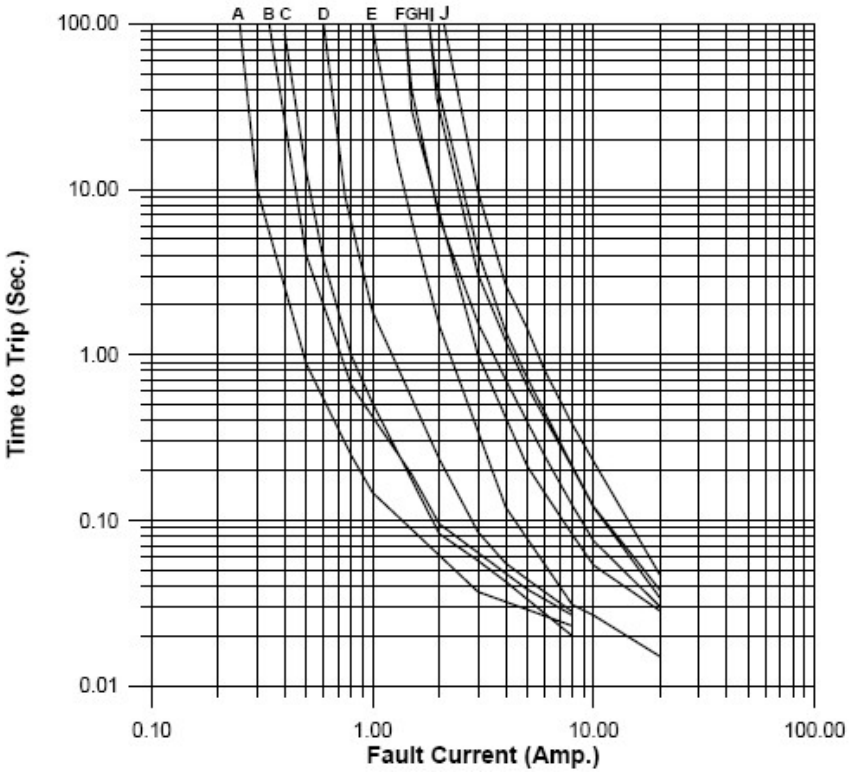
THERMAL DERATING CHART FOR SMD1812 SERIES-IHOLD(Amps) RECOMMENDED DATA

Model	Ambient Operation Temperature								
	-40℃	-20℃	0℃	23℃	40℃	50℃	60℃	70℃	85℃
1812-050	0.77	0.68	0.59	0.50	0.44	0.40	0.37	0.33	0.29

THERMAL DERATING CURVE FOR SMD1812 SERIES

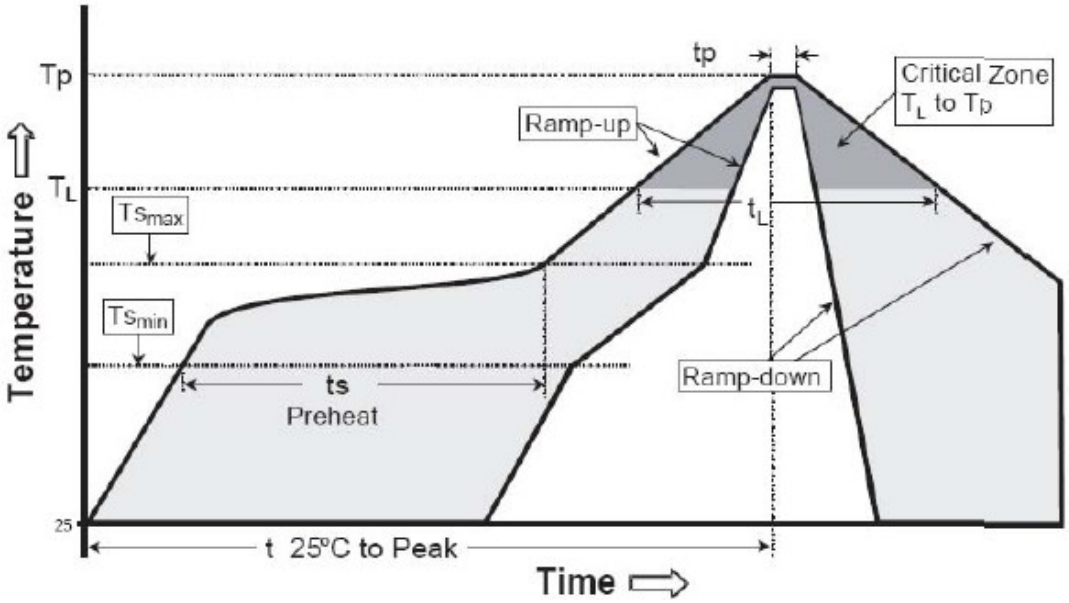


AVERAGE TIME-CURRENT CURVE FOR SMD1812 SERIES



A-SMD1812-010R
B-SMD1812-014R
C-SMD1812-020R
D-SMD1812-035R
E-SMD1812-050R
F-SMD1812-075R
G-SMD1812-075R
H-SMD1812-110R
I-SMD1812-110R
J-SMD1812-150R

SOLDER REFLOW



RECOMMENDED CONCITIONS

Profile Feature	Pd-Free Assembly
Average Ramp-Up Rate(Tsmax to Tp)	3℃/second max
Preheat —Temperature Min(Tsmin) —Temperature Max(Tsmax) —Time(Tsmin to Tsmax)	150℃ 200℃ 60-180seconds
Time maintained above： —Temperature(TL) —Time(tL)	217℃ 60-150seconds
Peak Temperature(Tp)	260℃
Time within 5℃ of actual Peak Temperature(tp)	20-40seconds
Ramp-Down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8minutes max.
Storage Condition	0℃~35℃，≤70%RH

Note：1.All temperature refer to topside of the package，measured on the package body surface.
2.If reflow temperature exceed the recommended profile，devices

PACKAGING

Part Number	Component Package	Quantity
1812-050	1812	1500

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